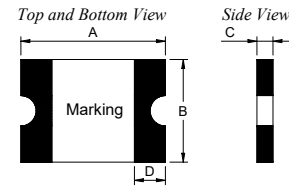


1、Physical Dimensions(size of 2920)

Unit:mm

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
LSMD300/30	6.73	7.98	4.80	5.44	0.70	1.50	0.30	T300



2、Electrical Characteristics

Part Number	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	T _{trip} (Max time to trip)		Pd _{typ} (W)	R _{min} (Ω)	R1 _{max} (Ω)
					Current(A)	Time(S)			
LSMD300/30	3.00	6.00	30	40	8.0	25	1.5	0.010	0.055

I_H: Holding Current: maximum current at which the device will not trip in 25°C still air.

I_T: Tripping Current minimum current at which the device will trip in 25°C still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

I_{max}: Maximum fault current device can withstand without damage at rated voltage.

T_{trip}: Maximum time to trip(s) at assigned current.

Pd_{typ}: Rated working power.

R_{min}: Minimum resistance of device prior to trip at 25°C.

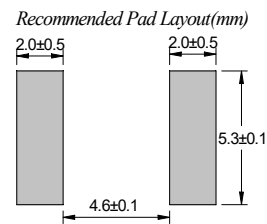
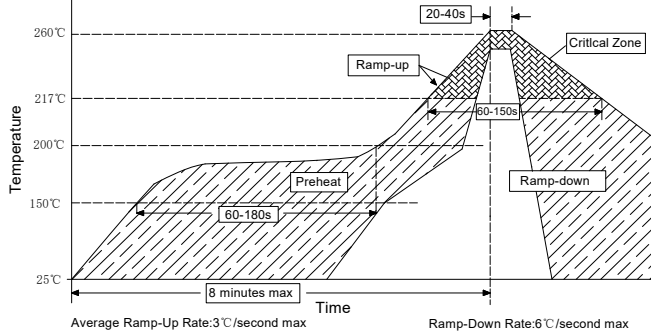
R1_{max}: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

3、Thermal Derating

LSMD300/30	Maximum ambient operating temperature								
	-40℃	-20℃	0℃	25℃	40℃	50℃	60℃	70℃	85℃
Hold Current(A)	4.53	4.02	3.51	3.00	2.52	2.26	1.99	1.75	1.34
Trip Current(A)	9.06	8.04	7.02	6.00	5.04	4.52	3.98	3.50	2.68

4、Solder Reflow Recommendations



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5、Package Information

Packing quantity: 1000PCS/Reel

Note: Reel packaging per EIA-481-2 standard